PDFN5X6-DUAL Package Type

1、封装结构与尺寸：

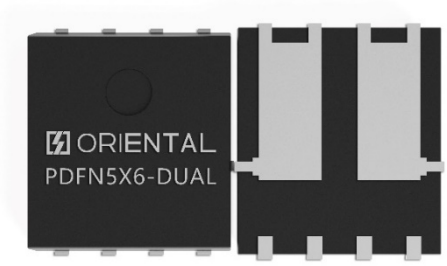
尺寸：通常为 5.00x6.00mm 或 5.15x6.15mm，与标准 PDFN5X6 封装尺寸一致，但内部集成两颗芯片，实现双通道功能。

散热设计：部分产品采用双面散热技术，通过顶部和底部金属层散热，降低热阻，提升散热效率，适用于高功率密度场景。

1. Package Structure and Dimensions

Dimensions: Typically measuring 5.00mm×6.00mm or 5.15mm×6.15mm, it is consistent with the standard PDFN5×6 package size. However, it integrates two chips internally to achieve dual-channel functionality.

Heat Dissipation Design: Some products adopt double-sided cooling technology, dissipating heat through the top and bottom metal layers. This design reduces thermal resistance, improves heat dissipation efficiency, and is suitable for high-power-density scenarios.



2、应用场景：

汽车电子：常用于新能源汽车的电池管理系统（BMS）、车载充电器（OBC）、DC-DC 转换器等，满足车规级可靠性要求，如符合 AEC-Q101 标准。

工业控制：适用于电机驱动、电源管理等对功率密度和散热要求较高的领域。

消费电子：部分产品用于快充芯片、电源适配器等，兼顾小型化与高效散热需求。

2. Application Scenarios

Automotive Electronics: It is commonly used in battery management systems (BMS), on-board chargers (OBC), and DC-DC converters for new energy vehicles, meeting automotive-grade reliability requirements such as compliance with the AEC-Q101 standard.

Industrial Control: It is suitable for fields with high requirements for power density and heat dissipation, such as motor drives and power management.

Consumer Electronics: Some products are applied in fast-charging chips and power adapters, balancing the needs for miniaturization and high-efficiency heat dissipation.

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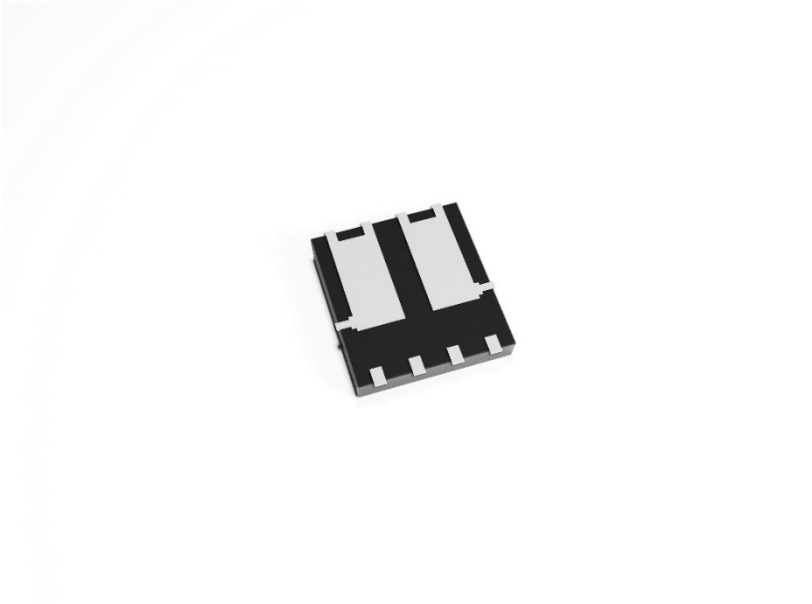


3、技术优势：

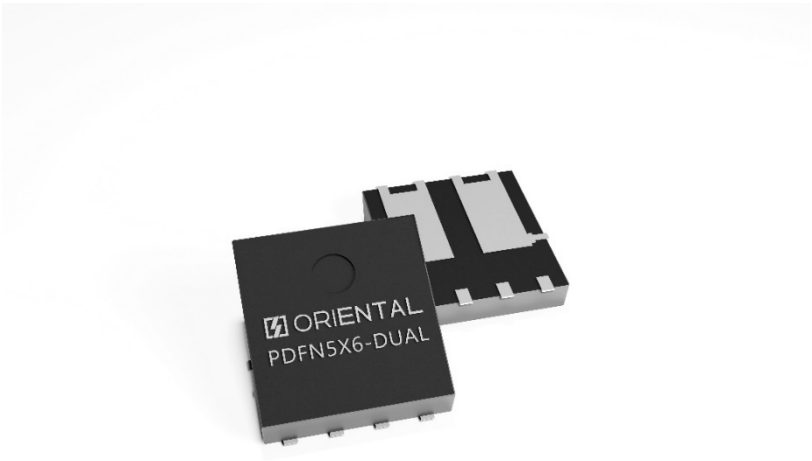
高集成度：双芯片设计减少外部电路连接，简化 PCB 布局，降低系统成本。

低热阻：双面散热或优化的散热结构，有效降低芯片工作温度，提升稳定性。

高可靠性：符合车规级标准，适应高温、高湿、高振动等恶劣环境。

3. Technical Advantages

- **High Integration**: The dual-chip design reduces external circuit connections, simplifies PCB layout, and lowers system costs.
- **Low Thermal Resistance**: Double-sided cooling or optimized heat dissipation structures effectively reduce the operating temperature of chips and enhance stability.
- **High Reliability**: Compliant with automotive-grade standards, it is capable of adapting to harsh environments such as high temperature, high humidity and high vibration.



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